October 21 (Wed.), 2026

[Oral 09] Sustainable CMP / Manufacturing Readiness

16:50-17:55

International Conference Hall (B1F)

● Session Chair: Knut Gottfried (Fraunhofer ENAS, Germany)

16:50-17:15 [Oral 09-1]

[Invited] CMP Challenges and Opportunities for 3D Silicon Photonics

Aurore Bonnevialle (STMicroelectronics, France), Catherine Euvrard, Clément Castan, Julian Sturm, Renan Bouis, Arnaud Cornelis (Univ. Grenoble Alpes, France), Elodie Beche, Sebastien Cremer, Sebastien Mermoz (STMicroelectronics, France), Carine Ladner, Stephane Nicolas, Sylvain Guerber, Amelie BelleminComte, Stephanie Garcia, Cédric Perrot (Univ. Grenoble Alpes, France), Frederic Boeuf, and Sébastien Petitdidier (STMicroelectronics, France)

17:15-17:35 [Oral 09-2]

CMP as a Key Enabling Process Step for SiGe BiCMOS, Silicon Photonics, and Quantum Technologies

Marco Lisker, Awwal Adeniyi Adesunkanmi, and Andreas Krüger (IHP GmbH - Leibniz Inst. for High Performance Microelectronics, Germany)

17:35-17:55 ★[Oral 09-3]

Recyclability of Cu/Ta Barrier Slurry via Ultrafiltration

Max Constantin Klotzsche, Conrad Guhl (Fraunhofer IPMS, Germany), and Frank Babick (Technische Univ. Dresden, Germany)